2019 NCAP & Yole Développement Symposium on

Advanced Packaging & System Integration Technology

APRIL 22 AND 23, 2019 – SHANGHAI, CHINA

Powered by YOLE Développement

Hosted by 华进半导体 NCAP CHINA

For the 5th edition, NCAP and Yole Développement combine their expertise to build an innovative program dedicated to the advanced packaging industry – during one day and a half, meet the leading executives and gain an in-depth understanding of the market evolution!
This year, it will take place in **Shanghai**, China, from **April 22PM to 23**, 2019.

AGENDA

Monday 22nd of April

11:30 AM – 1:00 PM: Registration

1:00 PM – 1:10 PM: Welcome and Introduction

1:10 PM – 1:45 PM: Market Briefing by Yole Développement
Market & Trends in High Ends Packaging
Emilie Jolivet, Division Director Semiconductor & Software – Yole Développement
Thibault Buisson, Chief Operating Officer – Yole Développement

1:45 PM – 3:45 PM: AI – HPC SESSION

1:45 PM – 2:30 PM – Keynote: Path to Move Forward
Farhang Yazdani, President & CTO – Broadpak

2:30 PM – 2:55 PM – High Performance Packaging for AI
John Lee, Sr. Director, Strategic Marketing, Greater China Sales & Marketing – Amkor Technology

2:55 PM – 3:20 PM – Substrate Solutions for AI and HPC
Dr. Dyi-Chung Hu, CEO – SiPlus

3:20 PM – 3:45PM – Title not available
Hougong Wang, Vice President, General Manager of PVD Divison – NAURA

3:45 PM – 4:30 PM: Coffee break – Networking time

4:30 PM – 6:35 PM: MEMORY & COMPUTING SESSION

4:30 PM – 4:55 PM – Advance in High Performance Flip Chip Packaging
Yaojian Lin, Vice President – JCET

4:55 PM – 5:20 PM – Heterogeneous Integration Package of IoT Applications
David Wang, Manager Product Application Engineering and Corporate R&D – SPIL

5:20 PM – 5:45 PM – Dual-Layer Temporary Bonding System for Advanced Packaging
Dongshun Bai, Ph.D., Deputy Business Development Director of the Wafer-Level Packaging Materials Business Unit – Brewer Science

5:45 PM – 6:10 PM – Inspection and Metrology Challenges for 3DIC Interconnect Scaling
Kevin Khoo, Marketing Director, Advanced Packaging, LS-Swift Division, Global Products Group – KLA Corporation

6:10 PM – 6:35 PM – Advances in Memory Packaging
Chan Pin Chong, Senior Vice President, EA/APMR & Wedge Bonders Business Units – Kulicke & Soffa

6:35 PM – 6:40 PM: Thank you and adjourn

6:40 PM – 8:40 PM: Networking cocktail and diner

Tuesday 23rd of April

8:15 AM – 8:45 AM: Market Briefing by Yole Développement
Advanced Packaging Trends in this Era of Digital New Age
Santosh Kumar, Principal Analyst and Director Packaging, Assembly & Substrates – Yole Korea
Favier Shoo, Technology and Market Analyst – Yole Développement

8:45 AM – 10:30 AM: TRANSPORTATION SESSION

8:45 AM – 9:15 AM – Keynote: SiP Packaging Technologies, Advantages and Applications
Yifan Guo, Vice President of Engineering – ASE Group

9:15 AM – 9:40 AM – AT&S All in One Package Solution
Lio Li, Front-End Engineering Manager/ECP Program Manager – AT&S China

9:40 AM – 10:05 AM – Ag-Sintering Die-Attach Technology Used for High Power Devices/Modules in Electrical Vehicles
Frank Boschman, Managing Director – Boschman Advanced Packaging Technology

10:05 AM – 10:30 AM – Not available

10:30 AM – 11:10 AM: Coffee break – Networking time

11:10 AM – 12:50 PM: 5G SESSION

11:10 AM – 11:35 AM – How 5G Will Influence and Drive Advanced Packaging Technologies
René Betschart, Senior Vice President Besi Products Asia & Besi Singapore – Besi

11:35 AM – 12:00 PM – Advanced RF Packaging Technology Trends, on the Way to 5G and mmWave Applications
Romain Fraux, CEO – System Plus Consulting

12:00 PM – 12:25 PM – Heterogeneous Integration SiP Technology Solution for 5G Era
Yasuhiro Morikawa, Senior Manager of Global Market & Technology Strategy Division – ULVAC

12:25 PM – 12:50 PM – Good and Bad News on the Way to 5G Era
Zhen'gang Pan, VP of New Radio Tech. – Unisoc

12:50 PM – 2:00 PM: Lunch – Networking Time

2:00 PM – 5:40 PM: CONSUMER SESSION

2:00 PM – 2:30 PM – Keynote: Enhanced IoT Edge by Smart Sensors
Bin Fu, Head of Business Development and Marketing China – Bosch Sensortec

2:30 PM – 2:55 PM – AI/IoT Era: Revolution in IC Design, Manufacturing, and Advanced Packaging
Min-Hwa Chi, Senior Vice President / TD – Sien (Qindao) Integated Circuit

2:55 PM – 3:20 PM – An Original Technique of Warpage Adjustment for FOWLP and FOPLP while in the Thermal Debonding Process
Debbie Claire Sanchez, FOWLP Equipment Product Manager – ERS Electronic

3:20 PM – 4:00 PM: Coffee break – Networking time

4:00 PM – 4:25 PM – Development of 2.5D /3D Integrated System and Wafer Level Fan-out Technology
Daping Yao, Ph.D., Technical Director – NCAP China

4:25 PM – 4:50 PM – Ubiquitous Display, the Golden Age of OLED
Zhisheng Li, Senior Researcher in X-Vision Lab – Visionox Technology

4:50 PM – 5:15 PM – Wafer Level Packaging and Heterogeneous Integration
Russell Liu, VP Sales & Marketing – China WLCSP

5:15 PM – 5:40 PM – Not available

5:40 PM – 5:55 PM: Thank you and adjourn